

SOT849-2

plastic quadruple in-line package; 90 leads; face down

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	QIP90
Package type industry code	QIP90
Package style descriptive code	QIP (quadruple in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	22-11-2004

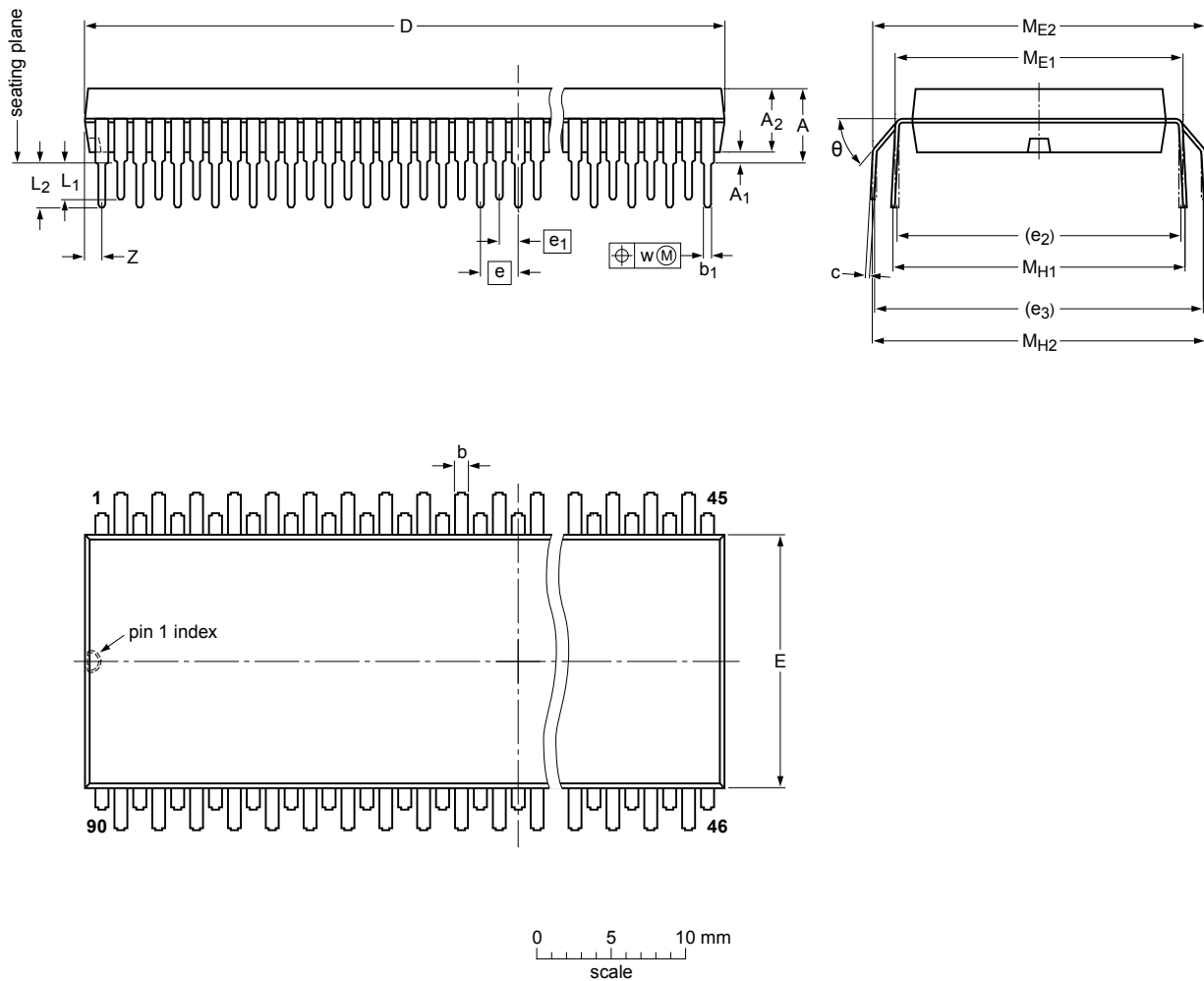
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	57.7	-	58.16	58.67	mm
E	package width	16.9	-	17	17.2	mm
A	seated height	[tbd]	-	5.79	5.79	mm
A ₂	package height	[tbd]	-	4.25	4.57	mm
n ₂	actual quantity of termination	-	-	90	-	



2. Package outline

QIP90: plastic quadruple in-line package; 90 leads; face down SOT849-2



DIMENSIONS (mm are the original dimensions)

UNIT	A max	A ₁ min	A ₂ max	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	e ₂	e ₃	L ₁	L ₂	ME ₁	ME ₂	M _{H1}	M _{H2}	w	Z ⁽¹⁾ max	θ
mm	5.79	0.46	4.57	1.07 0.67	0.56 0.40	0.32 0.23	58.67 57.70	17.2 16.9	2.54	1.27	19.05	22.05	3.0 2.6	3.2 2.8	19.60 19.05	22.65 22.10	20.78 19.53	23.58 22.33	0.18	1.7	55° 45°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT849-2						-04-03-08- 04-11-22

Fig. 1. Package outline QIP90 (SOT849-2)

3. Legal information

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